

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	27	("5001542" "5120665" "5356949" "5438223" "5633079" "5918113" "6034331" "6042894" "6172878" "6223429" "6328844").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:07
S3	288	hashimoto-nobuaki.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:12
S4	152008	thermal adj expansion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:08
S5	49	S3 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:08
S6	110	so! adj called adj epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:12
S7	3	so! adj called adj epoxy adj adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:14
S8	80	ascribable same binder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/15 22:17
S9	27	ascribable with binder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:26
S10	82139	coefficient near (thermal! adj expansion) cte	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:28

S11	1048323	chip die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:29
S12	2686339	substrate board	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:29
S13	5918	S10 with S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:29
S14	19188	S10 with S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:30
S15	3016	S13 with S14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:30
S16	4987047	higher lower	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:30
S17	279	S15 with S16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:30
S18	2430268	underfill adhesive resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:31
S19	76	S17 with S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:31
S20	6043263	@ad>"19990217" @rlad>"19990217" @pt1d>"19990217"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:32

S21	23	S19 not S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:39
S22	5843601	first second third	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:40
S23	216498	S22 with S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:41
S24	599	S23 with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:42
S25	135	S24 with S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:43
S26	43	S25 not S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:59
S27	133471	sided	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 13:59
S28	16990	S27 with adhesive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 14:00
S29	7	S28 with S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 14:46
S30	1071645	elast\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 14:46

S31	122	(S30 with S23 with S11) not S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 14:48
S32	5	(US-20010035586-\$).did. or (US-6017634-\$ or US-6541872-\$ or US-6455354-\$ or US-6049038-\$).did.	US-PGPUB; USPAT	OR	ON	2004/07/16 15:09

S33	107	("3877978" "3944123" "4113525" "4133525" "4342607" "4363076" "4432607" "4613660" "4692943" "4818823" "4933219" "4935086" "4988395" "5011546" "5045921" "5088189" "5118364" "5120371" "5128746" "5136365" "5140404" "5148266" "5167729" "5177134" "5196070" "5249971" "5256598" "5281281" "5286679" "5297333" "5304842" "5334260" "5355283" "5376403" "5385291" "5417771" "5436500" "5450283" "5466888" "5478700" "5497938" "5535509" "5536765" "5538789" "5539251" "5545465" "5545920" "5548091" "5565267" "5571340" "5571594" "5585438" "5594282" "5600183" "5605547" "5633529" "5656551" "5656862" "5659952" "5662262" "5668405" "5682064" "5684330" "5696033" "5706577" "5710071" "5716663" "5729049" "5733800" "5776796" "5786632" "5814180" "5814401" "5817545" "5818698" "5888606" "5998860" "5999413" "6007920" "6013946" "6017776" "6020629" "6048755" "6049129" "6051093" "6091140" "6099678" "6114753" "6158115" "6175159" "6198162" "6249052" "6252298" "6326700" "6331453").PN. OR ("2001/0035586" "6017634" "6049038" "6455354" "6541872").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/16 15:10
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S35	6043263	@ad>"19990217" @rlad>"19990217" @pt1d>"19990217"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:10
S36	94	S33 not S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:11
S37	82139	coefficient near (thermal! adj expansion) cte	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:11
S38	26	S37 and S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:19
S39	1048323	chip die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:22
S40	2430268	underfill adhesive resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:22
S41	5843601	first second third	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:22
S42	216498	S41 with S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:22
S43	8	(young\$ with S42 with S39) not S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:28
S44	1	1996-177739.NRAN.	DERWENT	OR	ON	2004/07/16 15:28
S45	2	("5629566").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/16 15:29

S46	49	("3401126" "3429040" "5315155" "5343076").PN. OR ("5629566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/16 15:29
S47	27	S46 not S35	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/16 15:57
S48	0	("620132331").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/16 15:58
S49	0	"620132331"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 15:58
S50	2	"62132331"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 16:01
S51	0	"40171970"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 16:01
S52	4	"4171970"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 16:01
S53	3	"04171970"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 19:57
S54	24740	micron.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 19:57
S55	9644	jiang.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 19:57
S56	278	S54 and S55	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 19:57

S57	64	S56 not S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 19:59
S58	13	S57 and (S37 or modulus)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:01
S59	4206	S37 with (young elastic\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:03
S60	665	S59 with S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:03
S61	352	S60 and S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:03
S62	100	S60 with S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:04
S63	39	S62 not S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:19
S64	457	schrock.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:19
S65	54	S54 and S64	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:19
S66	23	S65 not S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:19

S67	23	S66 not S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:20
S68	2	S67 and S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 20:20
S69	12	(US-20010035586-\$).did. or (US-6017634-\$ or US-6541872-\$ or US-6455354-\$ or US-6049038-\$ or US-5304842-\$ or US-6063649-\$ or US-5959363-\$ or US-5864178-\$ or US-5804882-\$).did. or (JP-10313022-\$ or JP-08055938-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2004/07/16 20:38
S70	0	"9227849"	US-PGPUB; USPAT; JPO	OR	ON	2004/07/16 20:38
S71	1	"09227849"	US-PGPUB; USPAT; JPO	OR	ON	2004/07/16 20:39
S72	2	"05013119"	US-PGPUB; USPAT; JPO	OR	ON	2004/07/16 20:48
S73	2	("5120665").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/16 21:33
S74	70525	tg	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 21:34
S75	443	S74 with S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 21:34
S76	74	S75 with S40	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 21:34

S77	43	S76 not S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/16 21:34
S78	12	(US-20010035586-\$).did. or (US-6017634-\$ or US-6541872-\$ or US-6455354-\$ or US-6049038-\$ or US-5304842-\$ or US-6063649-\$ or US-5959363-\$ or US-5864178-\$ or US-5804882-\$).did. or (JP-10313022-\$ or JP-08055938-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2004/07/19 19:39
S80	790495	printed circuit! adj board	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:55
S81	5345	interposer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:55
S82	173	S80 adj S81	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:55
S83	6051150	@ad>"19990217" @rlad>"19990217" @ptld>"19990217"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:56
S84	31	S82 not S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:56
S85	152026	thermal adj expansion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:56
S86	7	S84 and S85	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 19:56
S87	29	("4642889" "5218761" "5258648").PN. OR ("5491303"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/19 20:01

S88	17	S87 not S83	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/19 20:06
S89	1050	S80 with S81	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/19 20:06
S90	1043	S89 not S86	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/19 20:06
S91	299	S85 and S90	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/19 20:06
S92	68	S91 not S83	US-PGPUB; USPAT; USOCR	OR	ON	2004/07/19 20:41
S93	438693	molecular adj weight	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:43
S94	446377	silica	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:43
S95	4777	S93 with S94	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:44
S96	2430975	underfill adhesive resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:44
S97	794	S95 with S96	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:44
S98	526	S97 not S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:49
S99	1864832	integrated adj circuit semiconductor ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:49

S10 0	45	S98 and S99	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:51
S10 1	108	S93 with S85	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:51
S10 2	19	S101 and S99	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:52
S10 3	16	S102 not S83	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 20:52
S10 4	19	("5864178").URPN.	USPAT	OR	ON	2004/07/19 20:55
S10 5	6	underfill\$ with S93	USPAT	OR	ON	2004/07/19 20:55
S10 6	2	S105 not S83	USPAT	OR	ON	2004/07/19 21:08
S10 7	17	(US-20010035586-\$ or US-20010003049-\$).did. or (US-6017634-\$ or US-6541872-\$ or US-6455354-\$ or US-6049038-\$ or US-5304842-\$ or US-6063649-\$ or US-5959363-\$ or US-5864178-\$ or US-5804882-\$ or US-6063828-\$ or US-6057381-\$ or US-RE32958-\$).did. or (JP-10313022-\$ or JP-08055938-\$ or JP-411345928-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2004/07/20 15:58
S10 8	7	S93 and S107	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/19 21:08
S10 9	2	("5120665").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/20 17:33

S11 0	2721	tsukagoshi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 17:33
S11 1	6054341	@ad>"19990217" @riad>"19990217" @ptid>"19990217"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 17:34
S11 2	2291	S110 not S111	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 17:34
S11 3	204	tsukagoshi-isao.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 17:35
S11 4	191	S113 not S111	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 19:06
S11 5	2	("6049038").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/20 19:44
S11 6	20	(US-20010035586-\$ or US-20010003049-\$).did. or (US-6063649-\$ or US-5959363-\$ or US-5864178-\$ or US-5804882-\$ or US-6017634-\$ or US-6541872-\$ or US-6455354-\$ or US-6049038-\$ or US-5304842-\$ or US-RE32958-\$ or US-6057381-\$ or US-6063828-\$).did. or (JP-10313022-\$ or JP-08055938-\$ or JP-411345928-\$ or JP-11273771-\$ or JP-09312176-\$ or JP-03029207-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2004/07/20 19:44
S11 7	14	S116 and (modulus young elastic\$ soft\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 19:45

S11 8	598580	expansion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 19:46
S11 9	31505	S118 with (modulus young elastic\$ soft\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 19:46
S12 0	11	S119 and S116	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/20 19:46
S12 1	2	("5959363").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/22 19:58
S12 2	2	("6034331").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/22 20:21
S12 3	2	("5120665").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/22 20:21
S12 4	20	(US-20010035586-\$ or US-20010003049-\$).did. or (US-6017634-\$ or US-6541872-\$ or US-6455354-\$ or US-6049038-\$ or US-5304842-\$ or US-6063649-\$ or US-5959363-\$ or US-5864178-\$ or US-5804882-\$ or US-RE32958-\$ or US-6063828-\$ or US-6057381-\$).did. or (JP-10313022-\$ or JP-08055938-\$ or JP-411345928-\$ or JP-11273771-\$ or JP-09312176-\$ or JP-03029207-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2004/07/22 22:26
S12 5	12	S124 and soft\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/22 21:43

S12 6	6	S125 and modulus	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/07/22 21:45
S12 7	2	("5304842").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/22 22:03
S12 8	2	("6344696").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/22 22:26